MDCE Series
Molding SMD Power Inductors

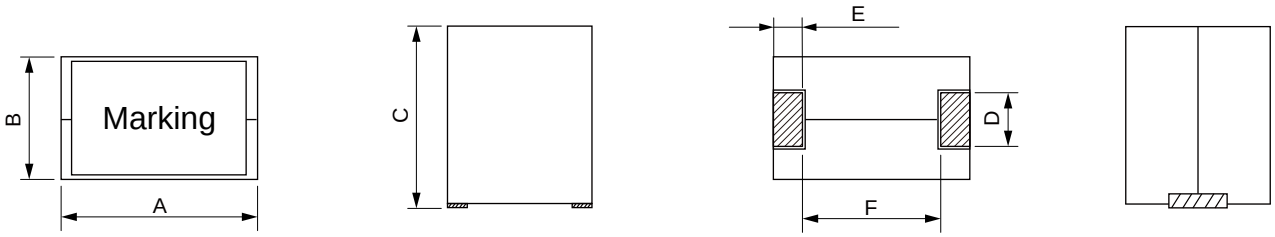
FEATURES

- High satura on characteris c core for large satura on current and low loss.
- Closed magne c circuit design reduces leakage flux.
- High precision DCR.
- Halogen Free & ROHS compliant.
- Opera ng temperature: -40 to +125 °C

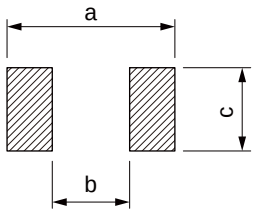
APPLICATION

- AI Servers, Data Centers, GPU/AI Accelerators.
- Desktop Motherboards, CPU/GPU Power Delivery.
- Mul -phase VRM, High-current DC-DC Converters.
- Networking Equipment, Communica on Infrastructure.

Dimensions: [mm]



Land Pattern: [mm]



Series	A	B	C	D	E	F	a	b	c
MDCE060610	6.5 max	6.5 max	10.0 max	3.7±0.2	1.75 typ	2.75 typ	7.2	2.6	4.2
MDCE090510	9.0 max	5.2 max	9.5 max	2.4 typ	2.50 typ	3.70 typ	9.2	3.4	3.0
MDCE100710	10.0 max	7.0 max	10.0 max	2.4±0.2	2.70 typ	4.60 typ	11.0	4.4	3.0

Electrical Properties:

Saturation Current will cause L0 to drop approximately 20%.
Temperature Rise 07Es The actutrivalue of DC con Currehen the t[(Temperatrre Ris)]T/C0/TT0 1<0B6>0%.BT/TT0 1(T=40 °C 20%. rg/T

Soldering Reflow:

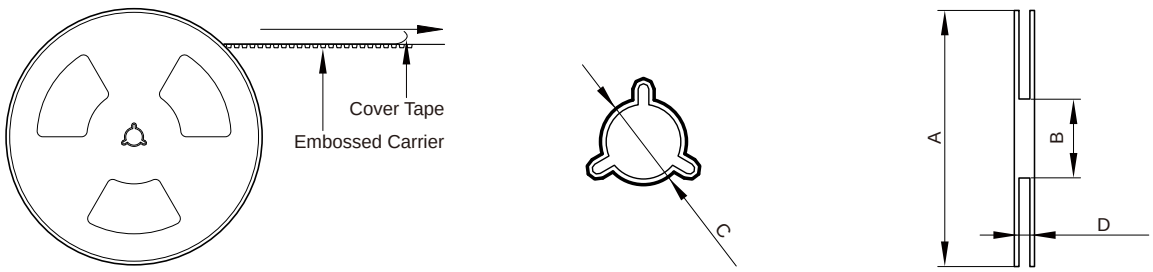
Packaging Information:

Tape Dimension: [mm]

Product Marking:

Marking	Printing Inductance)

Reel Dimension：[mm]



Series	A (mm)	B (mm)	C (mm)	D (mm)	Qty/Reel (pcs)
060610	330±1.0	100±1.0	13.2±0.5	24.5±0.2	
090510	330±1.0	100±1.0	13.2±0.5	24.5±0.2	
100710	330±1.0	100±1.0	13.2±0.5	24.5±0.2	

Cautions and Warnings:

Storage Conditions：

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max).If the storage period elapses, the soldering of the terminal electrodes may deteriorate.The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components.The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does.As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.